

AI Device Expo



Connecting Machine to Machine
WIRE Japan Show
Electrical / Optical Transmission Technology

Electronics Component & Unit Show

JEP Japan Federation of Electronic Parts Distributors and Dealers
TEA Tokyo Electronics Appliances Wholesalers Association



E-Textile / Wearable



The Exhibition Guide

2025.6.4 (Wed) → 6 (Fri) Tokyo Big Sight, East Exhibition Halls

The Total Solution Exhibition for Electronic Equipment 2025

Application to Exhibit from: 10:00 am (JST), November 1, 2024



Official Website

Organizers: Japan Electronics Packaging and Circuits Association, Japan Institute of Electronics Packaging, Japan Robot Association

Co-organizers: Electronic Device Industry News (Sangyo Times, Inc.)
Electric Wire & Cable News (KOGYO TSUSHIN CO., LTD)
Japan Federation Of Electronic Parts Distributors and Dealers
Tokyo Electronics Appliances Wholesalers Association
SENKEN SHIMBUN CO.,LTD.

Sponsor (tentative): Ministry of Economy, Trade and Industry

Overseas Cooperation:

World Electronic Circuits Council (WECC) Member Associates:
China Printed Circuit Association (CPCA), European Institute of Printed Circuits (EIPC),
Hong Kong Printed Circuit Association (HKPCA), IPC - Association Connecting Electronics Industries (IPC),
Indian Printed Circuit Association (IPCA), Electronic Industries Association of India (ELCINA),
Korea Printed Circuit Association (KPCA), Thailand Printed Circuit Association (THPCA),
Taiwan Printed Circuit Association (TPCA)

Association of Electronic Industries in Singapore (AEIS)
Korea Packaging Integration Association (KPIA)

As of Oct. 28, 2024

Come & Look WHAT we can OFFER for ELECTRONICS!!

400 exhibitors (tentative) wait you with cutting edge PCB, Assembly, Equipment, Process Materials and Components.

Exhibition Outline

Exhibition Period Wednesday, June 4 to Friday, June 6, 2025, 10:00 a.m. - 5:00 p.m.

Venue Tokyo Big Sight East Exhibition Halls

Managed by Japan Electronics Packaging and Circuits Association (JPCA)

Admission 1,000 Yen (including tax)




Secretariat Office JCS Communications, Inc.


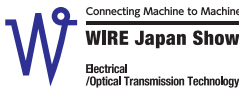


* Free Admission for those who have pre-registered online.

Attractive Seminar Programs/Events

PCB, Assembly, PCB Related Equipment, Materials/Processes, High-speed Transmission Technology for Autonomous Driving, High-current Technology for EVs, Advanced Packaging Technology, Materials and Process Technology for Power Semiconductors/Glass Substrates, Low-emission Technology for Climate Change, E-Textile/Wearable Technology, Sensor & Sensing Technology, Automated Technology/Solutions, Edge Computing, On-Device technology, etc.

Exhibitions held inside the exhibition/relevant exhibits

Electronic circuits technology	High-density packaging technologies	Electronic Component Packaging Technologies
 <p>JPCA 2025 Show 54th International Electronic Circuits Exhibition</p> <ul style="list-style-type: none"> ● PWB Tech Products and Technologies related to electronic circuit boards (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems), etc. ● Module JAPAN Module board / Module Board mounting / Embedded Component Board, General technology for built-in parts (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems), etc. ● Flexible Printed Circuits Products Area General technology for Flexible Printed Circuits (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) ● EMS Japan Services and technologies related to EMS, ODM and contract manufacturing of semiconductors (Design & Simulation, Reliability & Inspection, Circuit Board Materials, Functional & Process Materials, Manufacturing equipment, Related Systems) <p>Organizer: Japan Electronics Packaging and Circuits Association</p>	 <p>JIEP 2025 Microelectronics Show 39th ADVANCED ELECTRONICS PACKAGING EXHIBITION</p> <p>General technology for implementation and electric technology (Materials / Circuit and Mounting design / High speed high frequency / Electromagnetic properties / Electronic parts / mounting / Optical circuit mounting / Environmental affinity implementation / Semiconductor Package / Micro mechatronics mounting technology / Related Manufacturing equipment)</p> <p>Organizer: Japan Institute of Electronics Packaging</p>	 <p>JISSO PROTEC 2025 26th Jisso Process Technology Exhibition</p> <ul style="list-style-type: none"> ■ Electronic Component Placement Machines and related Equipment and Systems: electronic component placement machines (Mounter), electronic component insertion machines (Inserter), screen printers, soldering equipment (reflow oven), and dispensers ■ Packaging related Equipment and Systems: transfer systems, AGV, automatic warehouse, taping machines and materials, bulk feeders and other feeders, and automatic assembly machines, laser marking machine, cleaning equipment · cleaner ■ Semiconductor Packaging Machines and Systems: bonding equipment, flip chip packaging systems, COB systems ■ Industrial Robotics: handling robots, assembly robots, transport robots ■ Inspection/Test Equipment: automated optical inspection equipment, inspection/measuring equipment associated with semiconductor manufacturing ■ Packaging Design Systems: design tools, production optimizing software, and packaging programming equipment ■ Packaging Device Packaging Materials ■ Packaging Joining Systems · Solder/joining materials ■ High Frequency Compatible Devices, Components, and Materials ■ Environment related Devices and Materials <p>Organizer: Japan Robot Association</p>

AI Device	Electrical/optical transmission technology	Semiconductors and Electronic parts	Highly functional textile
 <p>AI Device Expo</p> <p>Smart devices, Smart home devices, Wearable devices, AI devices for robotics, AI devices for industrial robotics, Smart devices, Smart home devices, Wearable devices, AI devices for industrial robotics devices, AI devices for industrial robotics, Self-driving technology, AI software and platforms forms, Virtual assistants, Educational AI, Medical AI, Security AI, Data analysis tools, etc.</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Electronic Device Industry News (Sangyo Times, Inc.)</p>	 <p>WIRE Japan Show Electrical / Optical Transmission Technology</p> <p>General transmission technology for using wire and cable (Industrial equipment / Electrical wire, cable and connector / Electric wire processing machine / Wiring material / Wire Harness / Measuring instrument for electric wire and cable / Various devices + D116 / Inspection technology / M2M transmission / Optical transmission)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, Cable News (KOGYO TSUSHIN CO., LTD)</p>	 <p>Electronics Component & Unit Show Japan Federation of Electronic Parts Distributors and Dealers Tokyo Electronics Appliances Wholesalers Association</p> <p>General technology for solutions by Semiconductors and Electronic parts (Semiconductors / Electronic Devices / Sensors / Mechanical Devices / FA control equipments / Measuring instruments / Power Sources / IoT and M2M Solution / Manufacturing solution system)</p> <p>Co-organizers: Japan Federation Of Electronic Parts Distributors And Dealers, Tokyo Electronics Appliances Wholesalers Association</p>	 <p>E-Textile/Wearable</p> <p>A mix e-textile of electronic technology, fiber and clothing (General technology for smart textile, stretchable and wearable (Textile material / Conductive material / material / Knitting / weaving technology / Print marking technology / Films)</p> <p>Co-organizers: Japan Electronics Packaging and Circuits Association, SENKEN SHIMBUN CO., LTD.</p>

NEW Special Exhibition

If you wish to exhibit in the Special Exhibition, please select the zone when applying to exhibit.

Automotive Electronics Exhibition

Products and technologies related to automotive semiconductors

Chiplet Exhibition

Cutting-edge semiconductor and packaging related products and technologies

Medical and Healthcare Exhibition

Medical equipment, medical IT-related products and technologies

Startups and New Markets Exhibition

Electronics Ventures, E+Agriculture, E+Environment

Venue

Tokyo Big Sight East Exhibition Halls

Exhibit scale

438 companies / 1,230 booths

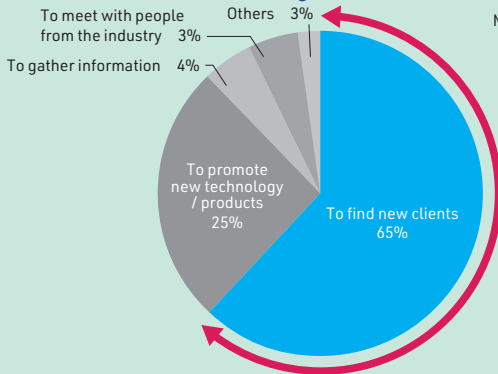
Number of visitors

48,334 people

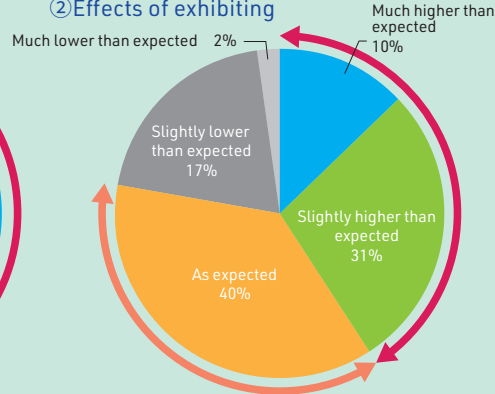
2024Exhibition Results

● Exhibitors Questionnaire

① Reasons for exhibiting

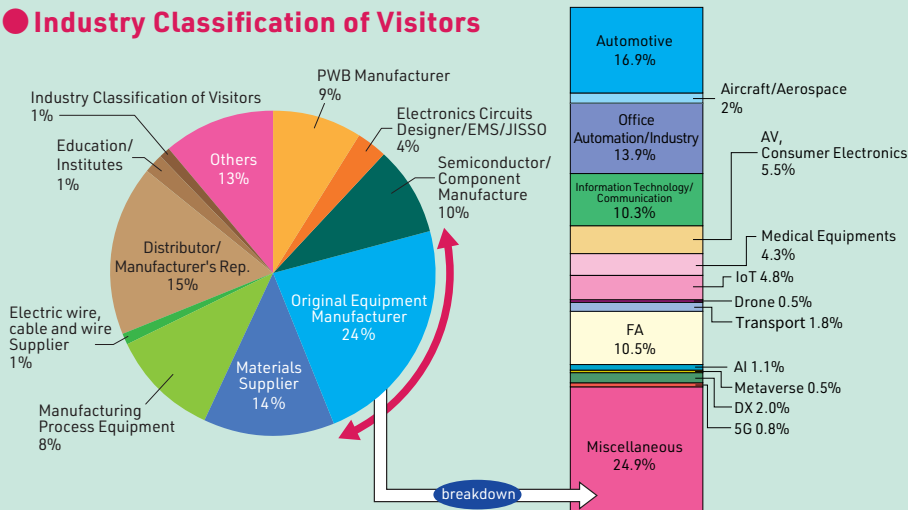


② Effects of exhibiting



Exhibited for the purpose of developing new customers, 41% of exhibitors exceeded expectations, 81% of exhibitors exceeded expectations.

● Industry Classification of Visitors



Not limited to traditional electronics and electrical equipment manufacturing visitors, networking with visitors from new application fields is expected. networking with visitors from new application fields is expected.

attention

Providing new networking opportunities!

"Student Welcome Booth" and "Exchange Plaza for Students" will be set up to welcome young generation that will be responsible for tomorrow's electronics!

Exhibitor Networking Meetings will be held to promote networking among exhibitors!

Expected VISITORS

Visitors from a wide variety of industries and Sectors!

Semiconductors, Telecommunications, Mobility (Automobiles, Motorcycles, Bicycles), Shipping, Trains, Aircraft, Agriculture, Transportation Infrastructure, Logistics, Gaming and Toys, Metaverse, AI, AR/VR, Forestry, Fisheries, Food, Education, Medical, Apparel/Sports Equipment, Finance, Local Government, Beauty, Smart Home Appliances, Defense Equipment, e-Sports, AV, Drones, Wearable Devices, Sensors, Disaster Prevention, Robotics, Biometrics, Energy, Dx/Gx/Cx/Sx, Tourism Dx, Signage, SmartX, etc.

AGC / Apple / EIZO / JSR / JVCケンウッド / KDDI / LG Electronics / LIXIL / NEC Group / NTT Group / Preferred Networks / Rapidus / SCREEN Holdings / SKJAPAN Group / TDK / THK / TOPPAN Group / TOTO / TSMC Group / YKK / AISIN / IRISOHYAMA / Asahi / ADVANTEST / Analog Devices / Amkor Technology Japan / U.S. Army / Alps Alpine / ISUZU MOTORS LIMITED / IBIDEN / Intel / USHIO / OMRON / OLYMPUS / OLYMPUS MEDICAL SYSTEMS / CASIO COMPUTER / Keyence / Kioxia / Canon / Canon Electronics / KING JIM / KUBOTA / Kuraray / Gunze / Konica Minolta / SAMSUNG DISPLAY / Samsung Japan / Suntory Holdings / CITIZEN group / Sharp / Japan Semiconductor / SUZUKI / STANLEY ELECTRIC / Seiko Group / Socionext / Sony Group / SoftBank / DAIKIN INDUSTRIES / DENSO / TOYOTA MOTOR / NIKON / Nichirei Logistics Engineering / nitori holdings / Nuvoton Technology Japan / PIONEER / Panasonic / paramount bed / FANUC / Fujikura / Bridgestone / BOSCH / Micron Technology / MinebeaMitsumi / MIRISE Technologies / Yamato Transport / Yamaha / Yamaha Motor / Ricoh / Renesas Electronics / Resonac / ROHTO Pharmaceutical / ROHM / AsahiKasei / YASKAWA Electric / ITOCHU / JAXA / Yokogawa Electric / Oki Electric Industry / Kao Corporation / HUAWEI / JMSDF / JCG / Marubeni / Iwatani / KYOCERA / Kintetsu World Express / Kumagagumi / Metropolitan Police Department / FURUKAWA ELECTRIC / EZAKI GLICO / YOKOTA AIR BASE / MITSUI / MITSUBISHI MOTORS / Mitsubishi Heavy Industries / Mitsubishi / Mitsubishi Electric / National Institute of Advanced Industrial Science and Technology / Shikoku Electric Power / SHISEIDO / KAJIMA / SHIBaura MECHATRONICS / SUMITOMO / Sumitomo Electric / Idemitsu / MOL Logistics / KOITO MANUFACTURING / Komori corporation / KOJIMA INDUSTRIES / Sunway Communication Japan / Shin-Etsu Chemical / New Energy and Industrial Technology Development Organization / SHINKO ELECTRIC / "Kobe Steel" / Nishitetsu Logistics / West Nippon Expressway / Nishi - Nippon Railroad / SEKISUI CHEMICAL / Kawasaki Heavy Industries / Sojitz / Kurabo Industries / SOHGO SECURITY SERVICES / "Murata Manufacturing" / TAIHEIYO CEMENT / TAIYO YUDEN / OSAKI ELECTRIC / Dai Nippon Printing / Oita Canon / OBAYASHI / DAIWA HOUSE INDUSTRY / Takenaka / Central Nippon Highway Engineering Tokyo / Asahi Shimbun / Nagase / HASEKO / Nagano Japan Radio / TEIJIN / DENTSU / SHIMADZU / Toray / DU PONT-TORAY / Toray Engineering / TOKAIRIKA / Central Japan Railway / TOKYU CONSTRUCTION / Tokyo Electron / Tokyo Electric Power Group / Toshiba Group / East Japan Railway / Tohoku Electric Power Network / TOYOB Group / Nissan Motor / NISSIN FOODS HOLDINGS / Nisshinbo / AMD Japan / Environmental Social and Governance / HP Japan / IBM Japan / Nihon Synopsys / Zeon / JT / Texas Instruments / Nikkei / Japan Aviation Electronics Industry / NIPPON EXPRESS / NEC Group / NIPPON TELEGRAPH AND TELEPHONE / JAPAN POST HOLDINGS / Hino Motors / Hitachi Group / Nintendo / NOHMI BOSAI / Forestry Agency / Hamamatsu Photonics / FUJIFILM / FUJI KYUKO / Fujitsu Group / FUJI ELECTRIC / U.S. Army / TOYODA GOSEI / TOYOTA INDUSTRIES / Toyota Tsusho / Defense Technology Foundation / National Defense Academy of Japan / Honda Motor / AJINOMOTO / MEIDENSHA / Nomura Research Institute / Nomura Securities / YAZAKI / RISO KAGAKU / JGSDF System & Signal/Cyber School

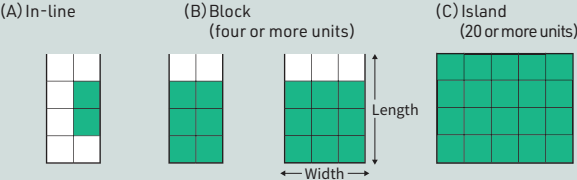
Exhibition Fee

Category	1 booth/9m ² *Tax included
Non-Members	Yen 496,100
Members ^{*1}	Yen 423,500

^{*1} Members of the following associations
WECC Member Associations (CPCA, EIPC, ELCINA, HKPCA, IPC, IPCA, KPCA, THPCA, TPCA)
AEIS, KPIA

- ※ Size of a booth is 9m² (3m × 3m).
- ※ Fee is for raw space only, Booth construction, cleaning, electricity, water supply, etc. are not included in the exhibition fee.

Booth type



※ In some cases, it may not be possible to prepare the requested booth type.

Assignment of Booth Locations

Booths will be assigned at the Booth Location Selection Meeting (Scheduled to be held in late March 2025).
As a rule, exhibitors will be able to choose their booth locations on a first-come-first-served basis.
※ For details, please refer to the Exhibitor Rules and Regulations.

Exhibitor Support Program

Option

Promotion services will provide an opportunity to increase your presence at the exhibition.

Application Deadline

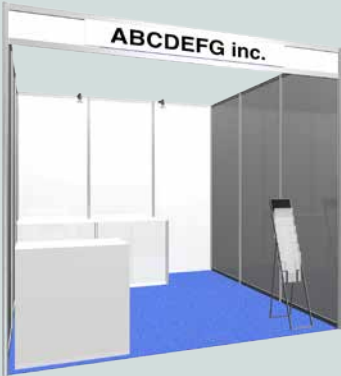
Friday, February 28, 2025

※ If all spaces are reserved before the deadline, the application will no longer be accepted.

Package booth

Option

● 1 booth / basic plan
Price: 121,000 Yen (Tax included)
This plan includes the minimum necessary booth fixtures and fittings, power supply and carpet.
For more details, please refer to the document to be distributed around mid-March 2025.



Cancellation charges

If an exhibit is cancelled to suit the exhibitor's circumstances, cancellation charges (full or partial fees) shall apply as below.

Date of receipt of written notice of cancellation	Cancellation charges
Until Friday, February 28, 2025	30% of booth fees
Saturday, March 1 - Monday, March 31, 2025	50% of booth fees
Tuesday, April 1 - Wednesday, April 30, 2025	70% of booth fees
From Thursday, May 1, 2025 onward	100% of booth fees

Schedule prior to the Exhibition (Tentative)

2024 November	2025 February	March	April	May	June
▲ November 1 (Fri.) 10:00 – Start of Exhibition Application	▲ February 28 (Fri.) Exhibitor application deadline	▲ Mid-March Exhibitor Manual available ▲ Late March Booth Location Selection Meeting	▲ Mid-April Sending Invitations Visitor Registration begins		▲ June 2 (Mon.) - 3 (Tue.) Installation period June 4 (Wed.) - June 6 (Fri.) Exhibition open ※ Immediate removal on the last day
Mid-March onwards Submission of necessary forms					

Managed by

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Official Website